

AMENDMENT TO THE CLAIMS:

Please amend the claims as follows:

1. (Currently amended) A method of manufacturing boards, ~~which the~~ method uses a prepreg and a metal foil to be laminated in laminating, the laminating comprising:

heating and pressing the prepreg and the metal foil at a given place via a mold-releasing sheet by a heat and press means;

removing the heat and the press applied by the heat and press means; [[and]]

cooling the prepreg and the metal foil, then peeling off the mold-releasing sheet, and

heating and pressing an entire face of the prepreg and the metal foil,

wherein, the heating and pressing the prepreg and the metal foil at a given place are performed at a temperature not lower than a softening point of a resin impregnated into the prepreg, while the temperature allows the resin to be kept in stage-B status.

2. (Currently amended) A method of manufacturing boards comprising:

laminating a first prepreg on a first metal foil;

heating and pressing the prepreg at a given ~~paee~~ place for bonding the first prepreg and the first metal foil together;

laminating a board having a circuit pattern on the first prepreg;

heating and pressing the board at a given place for bonding the first prepreg and the board together;

laminating ~~another~~ a second prepreg on the board;

heating and pressing the ~~another~~ second prepreg at a given place for bonding the ~~another~~ second prepreg and the board together;

laminating ~~another~~ a second metal foil on the ~~another~~ second prepreg;

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heating and pressing the ~~another~~ second metal foil at a given place for bonding the ~~another~~ second metal foil and the ~~another~~ second prepreg together to form a laminate; and

heating and pressing an entire face of ~~a unit laminated hereinbefore~~ the first prepreg, the first metal foil, the board, the second prepreg and the second foil to bond the laminate together,

wherein ~~a method of the~~ the heating and pressing ~~prepreg~~ at the given place includes:

heating and pressing ~~the prepreg at the given place~~ via a mold-releasing sheet by a heat and press means at a temperature not lower than a softening point of a resin impregnated into the prepreg, while the temperature allows the resin to be kept in stage-B status;

removing the heat and press applied by the heat and press means; and

cooling ~~the prepreg, then~~ and peeling off the mold-releasing sheet.

3. (Original) The manufacturing method as defined in claim 1, wherein the laminating, in which the prepreg is used to be laminated, laminates a metal foil on the prepreg, laminates a board on the prepreg, or laminates a prepreg on the prepreg.

4. (Currently amended) The manufacturing method as defined in claim ~~[[1]]~~ 2, wherein the board having a circuit pattern is a composite of thermosetting resin and one of woven fiber or non-woven fiber.

5. (Original) The manufacturing method as defined in claim 1 or claim 2, wherein the prepreg has base material impregnated with resin, and the resin is kept in stage-B status.

6. (Canceled)

7. (Currently amended) The manufacturing method as defined in claim 1 or claim 2, wherein the peeling off of the mold-releasing sheet ~~peels~~ includes peeling off the sheet from one ~~[[side]]~~ end of the sheet ~~gradually and sequentially~~ toward another ~~side~~ end.

8-28. (Cancelled)